PIA060K12Q-P33-EB Foxconn 12VDC 60mm 3.00A Server Fan Datasheet

Brand: Foxconn

SKU: 672717092472

Category: Axial & Centrifugal Fans

Price: **$23.99**

E-mail: sales@equipspares.com

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Product Page:
https://www.equipspares.com/product/pia060k12q-p33-eb-foxconn-12vdc-60mm-3-00a-server-fan

Product Description

The Foxconn PIA060K12Q-P33-EB is a specialized high-performance server cooling fan designed for mission-critical thermal management in enterprise hardware. Engineered with a robust DC brushless motor and precision dual ball bearing architecture, this unit ensures exceptional longevity and structural rigidity under continuous high-load operations. The aerodynamic blade geometry is optimized to overcome high system impedance, delivering substantial static pressure required for dense server chassis environments like the Dell PowerEdge series. Its advanced thermal design minimizes heat accumulation, ensuring component stability and operational efficiency in restricted airflow zones.

Model Number: PIA060K12Q-P33-EB
Brand: Foxconn
Product Type: High Performance Server Axial Fan
OEM Part Number: 0XD7N7
Compatible Series: Dell PowerEdge R750, R750Xa, R750xs, R7525
Rated Voltage: 12V DC
Rated Current: 3.00 A
Power Consumption: 36.0 W
Bearing Type: Dual Ball Bearing
Frame Size: 60mm Class

Speed Control: PWM (Pulse Width Modulation)
Signal Output: Tachometer (Frequency Generator)
Connector Type: Proprietary Server Hot-Swap / 4-Pin Header
Housing Material: Reinforced PBT (UL94V-0)
Blade Material: Reinforced PBT (UL94V-0)
Operating Temperature: -10°C to +70°C
Application Profile: High Static Pressure / High Airflow
Safety Approvals: CE, TUV, UL

The PIA060K12Q-P33-EB is specifically engineered for integration into high-density computing environments, serving as a primary cooling solution for the Dell PowerEdge R750 and R750Xa server families. In these data center applications, the PIA060K12Q-P33-EB manages thermal loads generated by high-performance processors and redundant power supplies, ensuring optimal airflow through restricted chassis zones. Its robust design makes it suitable for continuous operation in enterprise rack systems, telecommunications equipment, and other industrial computing platforms requiring reliable heat dissipation.

Supplemental Images